

**PATENT**

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**ABSTRACT OF THE DISCLOSURE**

[0029] Embodiments of the invention generally provide methods for removing a residue from a substrate surface, comprising mixing an aqueous solution with a hydrogen peroxide solution to produce a cleaning solution. The aqueous solution comprises sulfuric acid and hydrofluoric acid. A portion of the cleaning solution is applied to residue and the substrate surface a period. The portion of the cleaning solution is rinsed from the substrate surface with water to form a wash solution. The wash solution is discarded following cleaning of each wafer.